

# E3M0160120J2

Silicon Carbide Power MOSFET  
E-Series Automotive  
N-Channel Enhancement Mode



## Features

- 3rd generation SiC MOSFET technology
- Optimized package with separate driver source pin
- 4.7mm of creepage distance between drain and source
- High blocking voltage with low on-resistance
- High-speed switching with low capacitances
- Fast intrinsic diode with low reverse recovery ( $Q_{rr}$ )
- Halogen free, RoHS compliant
- Automotive Qualified (AEC-Q101) and PPAP Capable

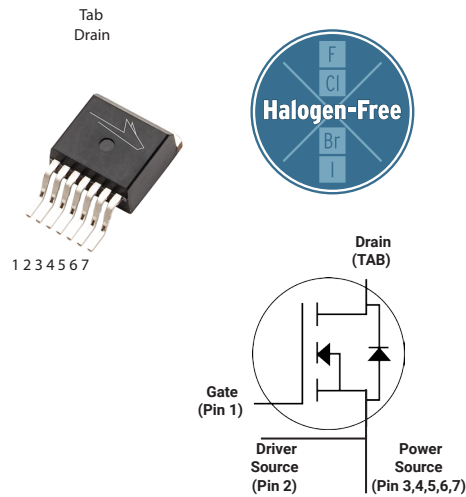
## Benefits

- Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Reduce cooling requirements
- Increase power density
- Increase system switching frequency

## Applications

- Motor Control
- EV Battery Chargers
- High Voltage DC/DC Converters

## Package



Part Number	Package	Marking
E3M0160120J2	TO-263-7XL	E3M0160120J2

Maximum Ratings ( $T_c = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Value	Unit	Note
$V_{DSmax}$	Drain - Source Voltage	1200	V	
$V_{GSmax}$	Gate - Source Voltage	-8/+19	V	Note: 1
$I_D$	Continuous Drain Current, $V_{GS} = 15\text{ V}$	$T_c = 25^\circ\text{C}$	18	A Fig. 19 Note: 2
		$T_c = 100^\circ\text{C}$	14	
$I_{D(pulse)}$	Pulsed Drain Current, Pulse width $t_p$ limited by $T_{jmax}$	34	A	Fig. 22
$P_D$	Power Dissipation, $T_c=25^\circ\text{C}$ , $T_j = 175^\circ\text{C}$	104	W	Fig. 20 Note: 2
$T_j, T_{stg}$	Operating Junction and Storage Temperature	-55 to +175	$^\circ\text{C}$	
$T_L$	Solder Temperature, 1.6mm (0.063") from case for 10s	260	$^\circ\text{C}$	

Note (1): Recommended turn off / turn on gate voltage  $V_{GS} = -4V...0V / +15V$

Note (2): Verified by design


**Electrical Characteristics** ( $T_c = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	1200			V	$V_{GS} = 0\text{ V}, I_D = 100\text{ }\mu\text{A}$	
$V_{GS(th)}$	Gate Threshold Voltage	1.8	2.8	3.8	V	$V_{DS} = V_{GS}, I_D = 2.33\text{ mA}$	Fig. 11
			2.2		V	$V_{DS} = V_{GS}, I_D = 2.33\text{ mA}, T_J = 175^\circ\text{C}$	
$I_{DSS}$	Zero Gate Voltage Drain Current		1	50	$\mu\text{A}$	$V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}$	
$I_{GSS}$	Gate-Source Leakage Current		10	250	nA	$V_{GS} = 15\text{ V}, V_{DS} = 0\text{ V}$	
$R_{DS(on)}$	Drain-Source On-State Resistance		159	208	m $\Omega$	$V_{GS} = 15\text{ V}, I_D = 8.5\text{ A}$	Fig. 4, 5, 6
			280			$V_{GS} = 15\text{ V}, I_D = 8.5\text{ A}, T_J = 175^\circ\text{C}$	
$g_{fs}$	Transconductance		4.9		S	$V_{DS} = 20\text{ V}, I_{DS} = 8.5\text{ A}$	Fig. 7
			4.6			$V_{DS} = 20\text{ V}, I_{DS} = 8.5\text{ A}, T_J = 175^\circ\text{C}$	
$C_{iss}$	Input Capacitance		730		pF	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V to } 1000\text{ V}$ $f = 1\text{ MHz}$ $V_{AC} = 25\text{ mV}$	Fig. 17, 18
$C_{oss}$	Output Capacitance		31				
$C_{rss}$	Reverse Transfer Capacitance		2				
$E_{oss}$	$C_{oss}$ Stored Energy		17		$\mu\text{J}$	$V_{DS} = 1000\text{ V}, f = 1\text{ MHz}$	Fig. 16
$C_{o(er)}$	Effective Output Capacitance (Energy Related)		36		pF	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ to } 800\text{ V}$	Note: 3
$C_{o(tr)}$	Effective Output Capacitance (Time Related)		55		pF		
$E_{ON}$	Turn-On Switching Energy (Body Diode FWD)		151		$\mu\text{J}$	$V_{DS} = 800\text{ V}, V_{GS} = -4\text{ V}/15\text{ V}, I_D = 8.5\text{ A},$ $R_{G(ext)} = 2.5\text{ }\Omega, L = 404\text{ }\mu\text{H}, T_J = 175^\circ\text{C}$ FWD = Internal Body Diode	Fig. 26, 28
$E_{OFF}$	Turn-Off Switching Energy (Body Diode FWD)		8				
$t_{d(on)}$	Turn-On Delay Time		7		ns	$V_{DD} = 800\text{ V}, V_{GS} = -4\text{ V}/15\text{ V}, I_D = 8.5\text{ A},$ $R_{G(ext)} = 2.5\text{ }\Omega, L = 404\text{ }\mu\text{H}, T_J = 175^\circ\text{C}$ Timing relative to $V_{DS}$ Inductive load	Fig. 27, 28
$t_r$	Rise Time		9				
$t_{d(off)}$	Turn-Off Delay Time		12				
$t_f$	Fall Time		11				
$R_{G(int)}$	Internal Gate Resistance		5.1		$\Omega$	$f = 1\text{ MHz}, V_{AC} = 25\text{ mV}$	
$Q_{gs}$	Gate to Source Charge		11		nC	$V_{DS} = 800\text{ V}, V_{GS} = -4\text{ V}/15\text{ V}$ $I_D = 8.5\text{ A}$ Per IEC60747-8-4 pg 21	Fig. 12
$Q_{gd}$	Gate to Drain Charge		10				
$Q_g$	Total Gate Charge		28				

Note (3):  $C_{o(er)}$ , a lumped capacitance that gives same stored energy as  $C_{oss}$  while  $V_{ds}$  is rising from 0 to 800V

$C_{o(tr)}$ , a lumped capacitance that gives same charging time as  $C_{oss}$  while  $V_{ds}$  is rising from 0 to 800V

Reverse Diode Characteristics ( $T_c = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$V_{SD}$	Diode Forward Voltage	4.8		V	$V_{GS} = -4\text{ V}, I_{SD} = 4.25\text{ A}, T_J = 25^\circ\text{C}$	Fig. 8, 9, 10
		4.2		V	$V_{GS} = -4\text{ V}, I_{SD} = 4.25\text{ A}, T_J = 175^\circ\text{C}$	
$I_S$	Continuous Diode Forward Current		17	A	$V_{GS} = -4\text{ V}, T_c = 25^\circ\text{C}$	
$I_{S, \text{pulse}}$	Diode pulse Current		34	A	$V_{GS} = -4\text{ V}$ , pulse width $t_p$ limited by $T_{J\text{max}}$	
$t_{rr}$	Reverse Recover time	8		ns	$V_{GS} = -4\text{ V}, I_{SD} = 8.5\text{ A}, V_R = 800\text{ V}$ $di_F/dt = 6820\text{ A}/\mu\text{s}, T_J = 25^\circ\text{C}$	
$Q_{rr}$	Reverse Recovery Charge	111		nC		
$I_{rm}$	Peak Reverse Recovery Current	25		A		
$t_{rr}$	Reverse Recover time	10		ns	$V_{GS} = -4\text{ V}, I_{SD} = 8.5\text{ A}, V_R = 800\text{ V}$ $di_F/dt = 2230\text{ A}/\mu\text{s}, T_J = 25^\circ\text{C}$	
$Q_{rr}$	Reverse Recovery Charge	42		nC		
$I_{rm}$	Peak Reverse Recovery Current	8		A		

## Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	1.11	1.44	$^\circ\text{C}/\text{W}$		Fig. 21



## Typical Performance

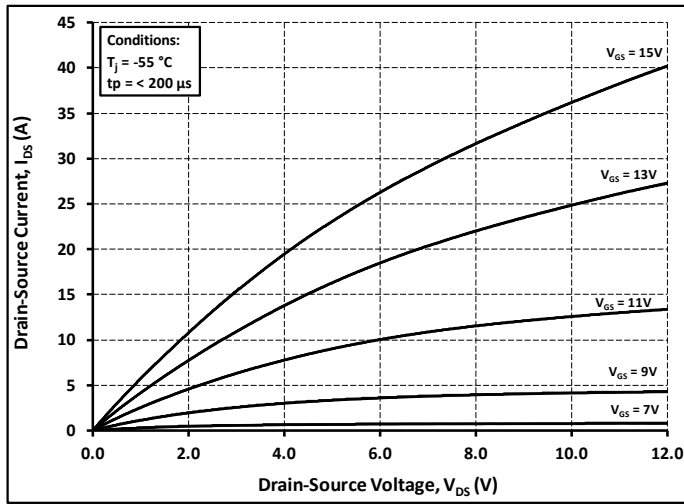
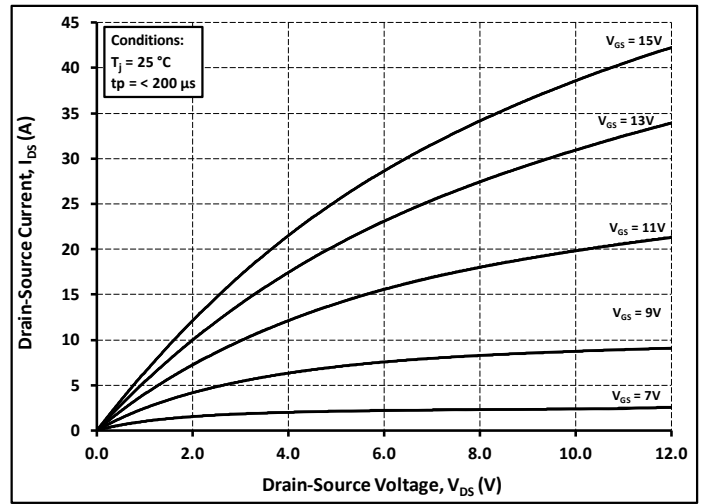
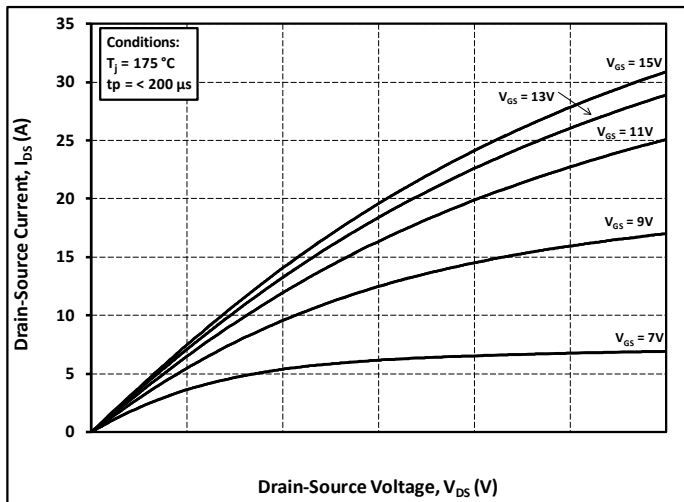
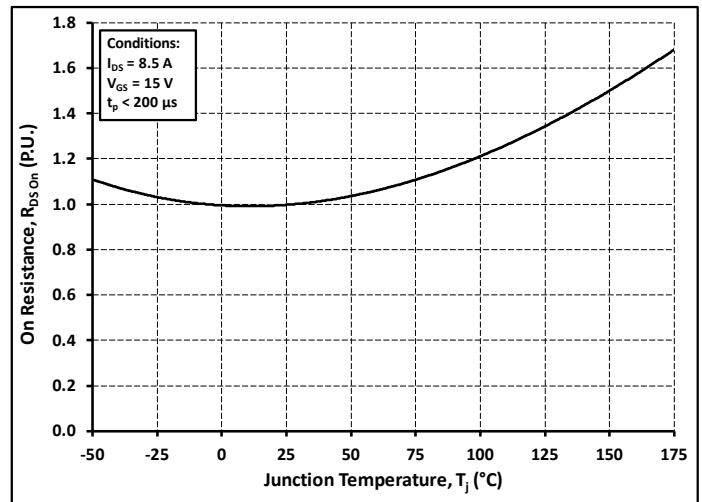
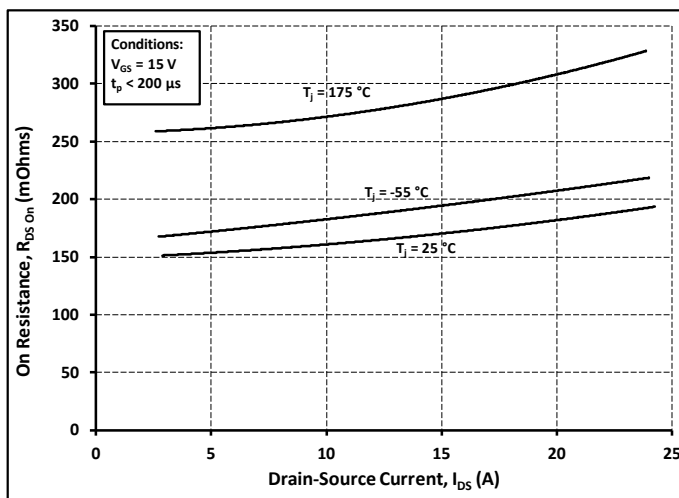
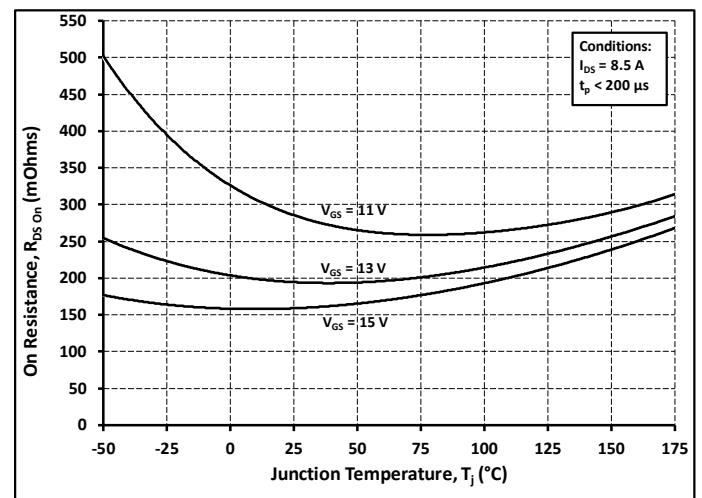
Figure 1. Output Characteristics  $T_j = -55\text{ }^{\circ}\text{C}$ Figure 2. Output Characteristics  $T_j = 25\text{ }^{\circ}\text{C}$ Figure 3. Output Characteristics  $T_j = 175\text{ }^{\circ}\text{C}$ 

Figure 4. Normalized On-Resistance vs. Temperature

Figure 5. On-Resistance vs. Drain Current  
For Various TemperaturesFigure 6. On-Resistance vs. Temperature  
For Various Gate Voltage

## Typical Performance

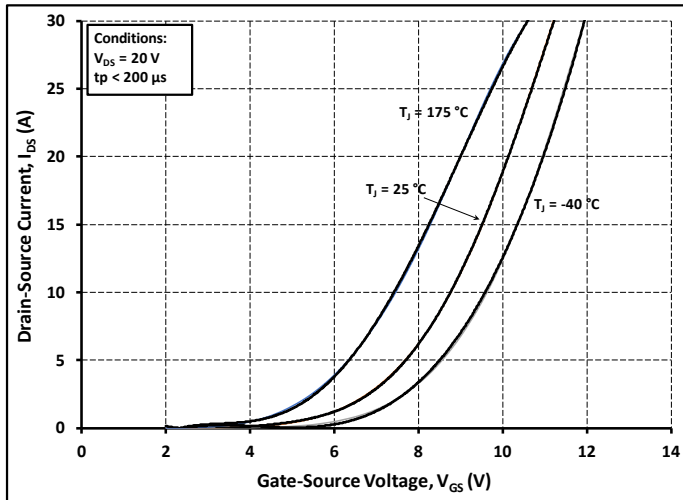


Figure 7. Transfer Characteristic for Various Junction Temperatures

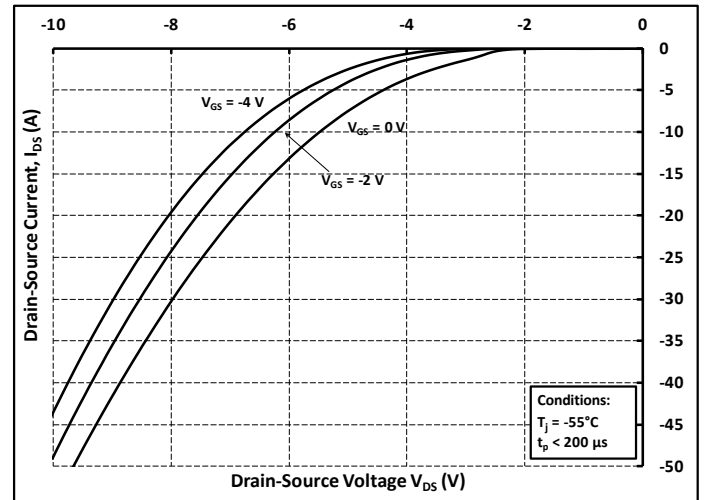
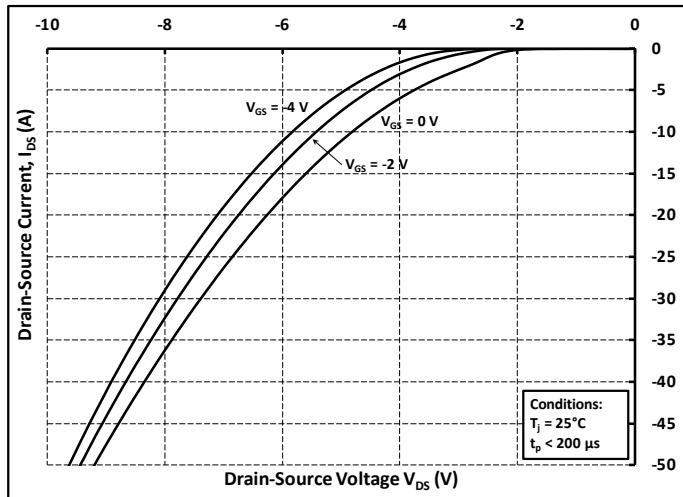
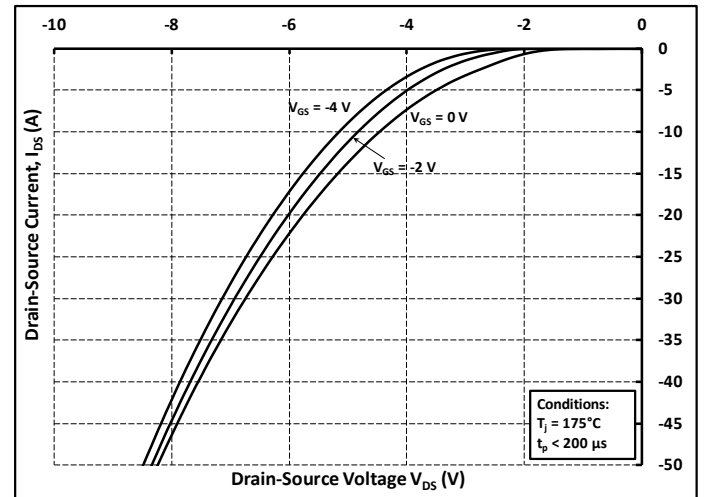
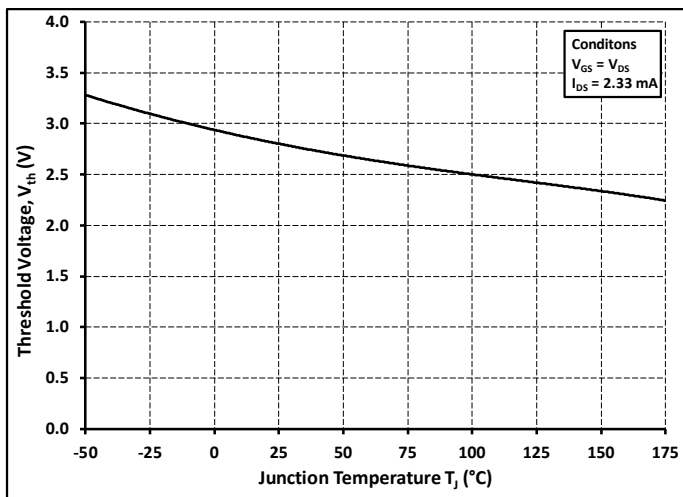
Figure 8. Body Diode Characteristic at  $-55\text{ }^{\circ}\text{C}$ Figure 9. Body Diode Characteristic at  $25\text{ }^{\circ}\text{C}$ Figure 10. Body Diode Characteristic at  $175\text{ }^{\circ}\text{C}$ 

Figure 11. Threshold Voltage vs. Temperature

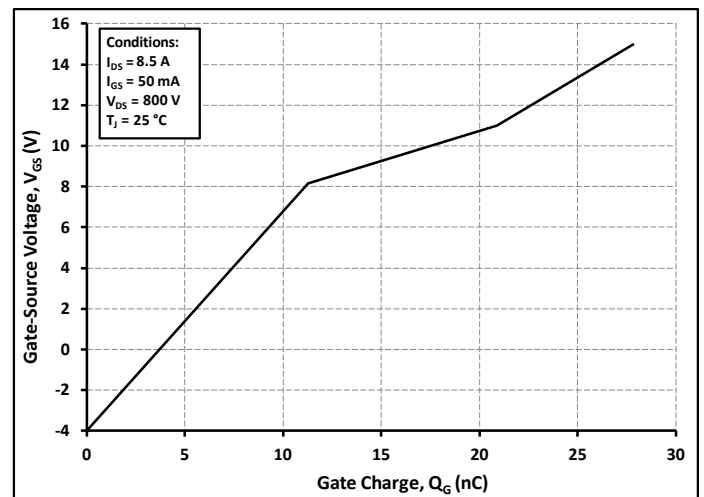


Figure 12. Gate Charge Characteristics

## Typical Performance

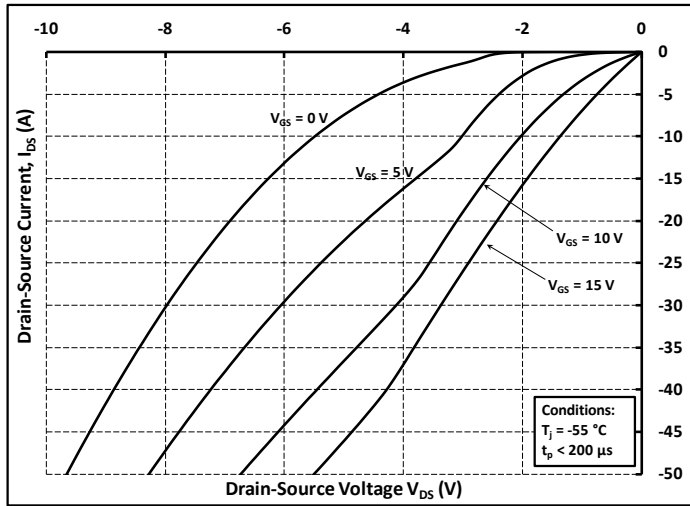
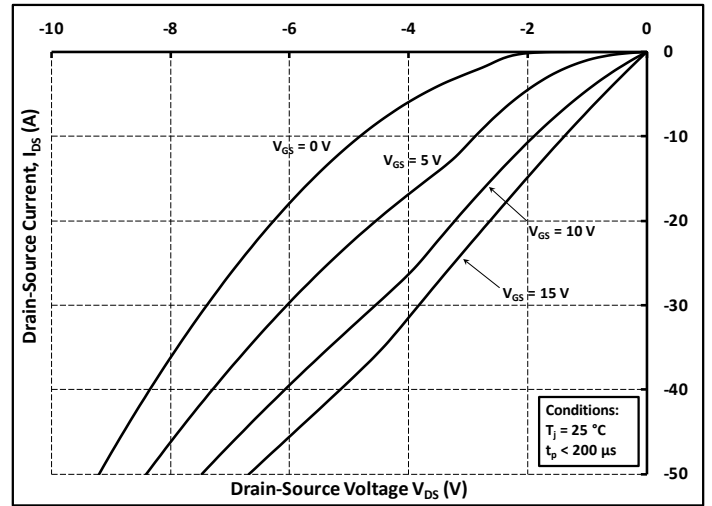
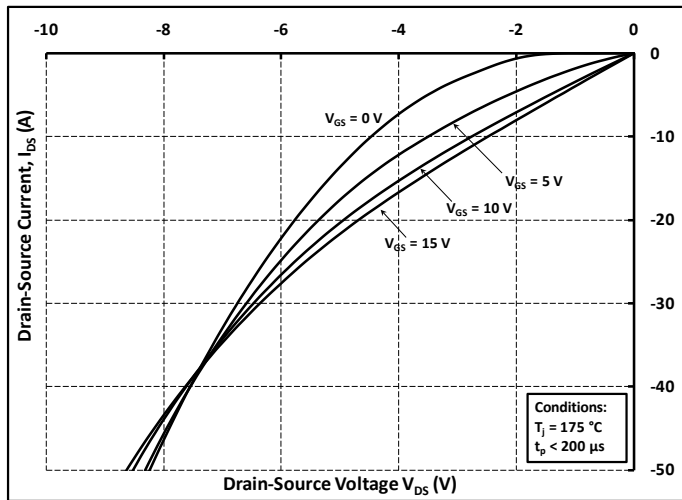
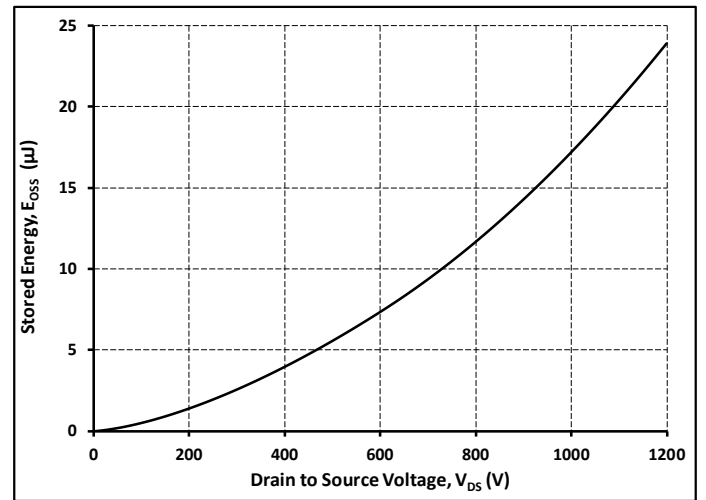
Figure 13. 3rd Quadrant Characteristic at  $-55\text{ }^{\circ}\text{C}$ Figure 14. 3rd Quadrant Characteristic at  $25\text{ }^{\circ}\text{C}$ Figure 15. 3rd Quadrant Characteristic at  $175\text{ }^{\circ}\text{C}$ 

Figure 16. Output Capacitor Stored Energy

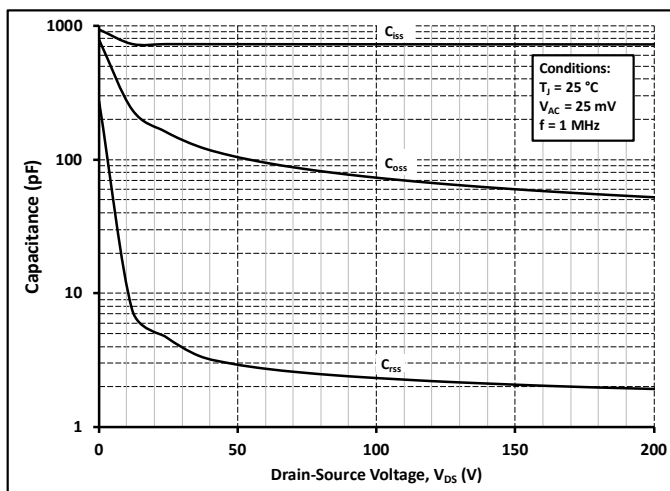


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

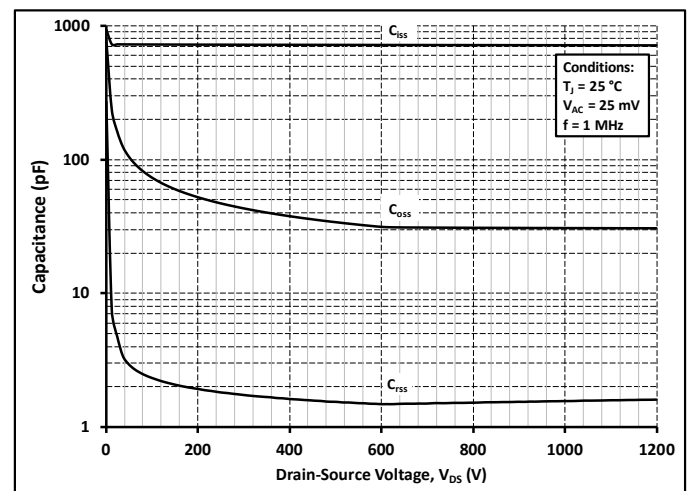


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1200V)

## Typical Performance

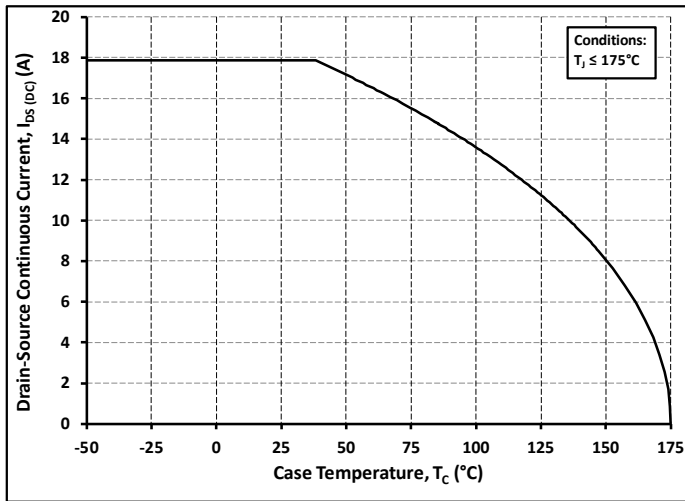


Figure 19. Continuous Drain Current Derating vs. Case Temperature

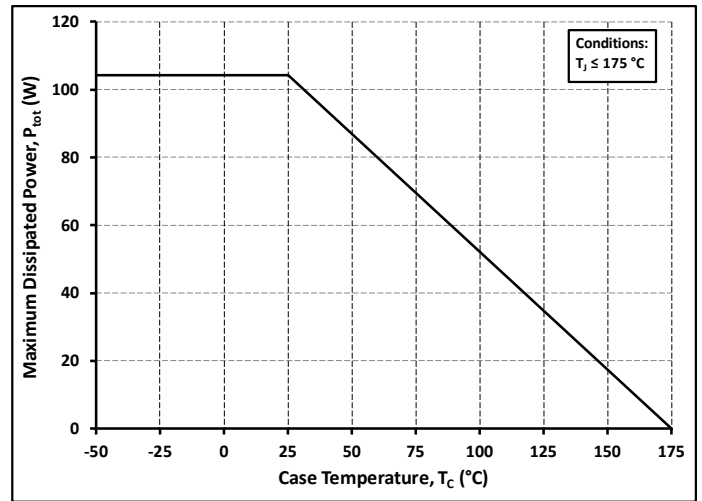


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

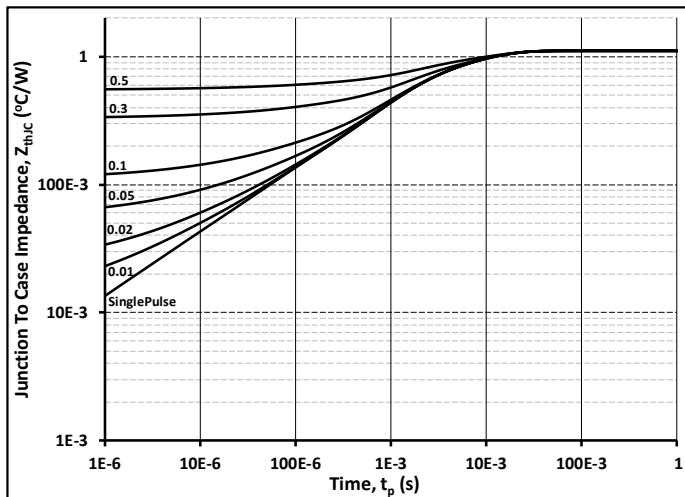


Figure 21. Transient Thermal Impedance (Junction - Case)

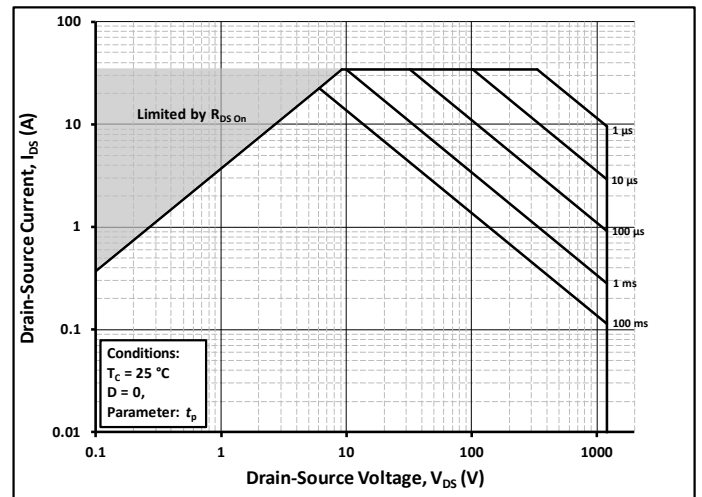
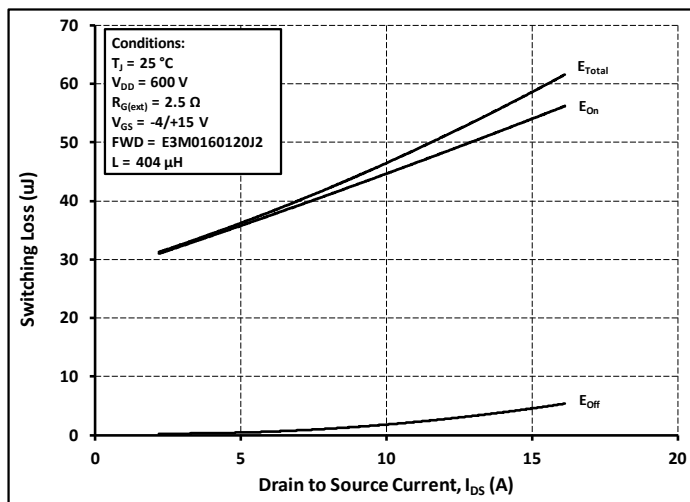
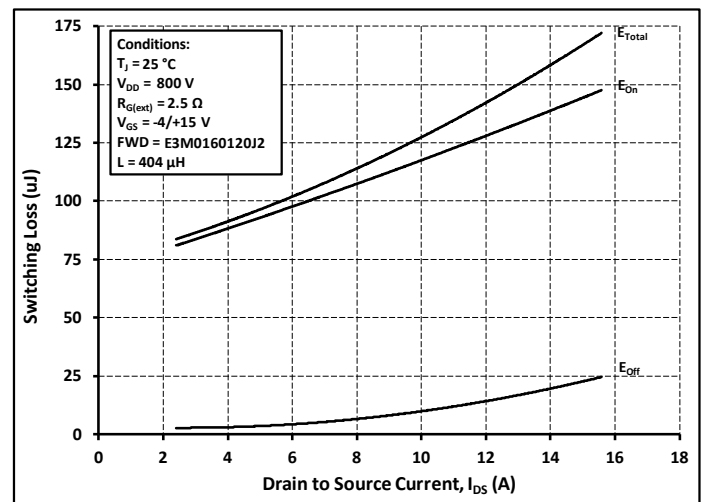


Figure 22. Safe Operating Area

Figure 23. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 600V$ )Figure 24. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 800V$ )

## Typical Performance

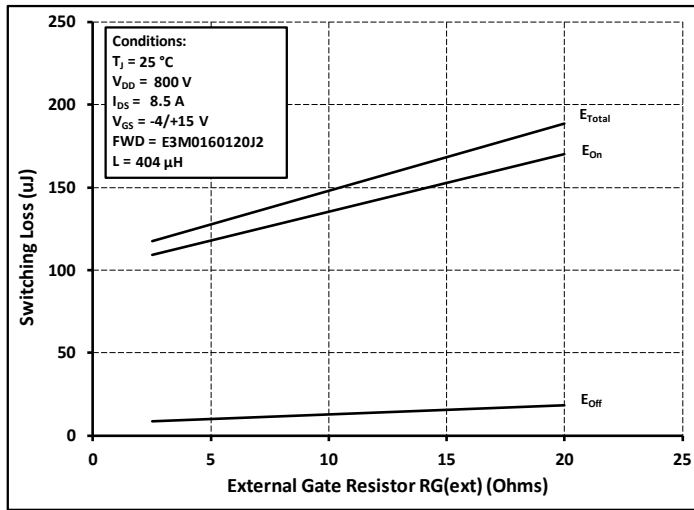
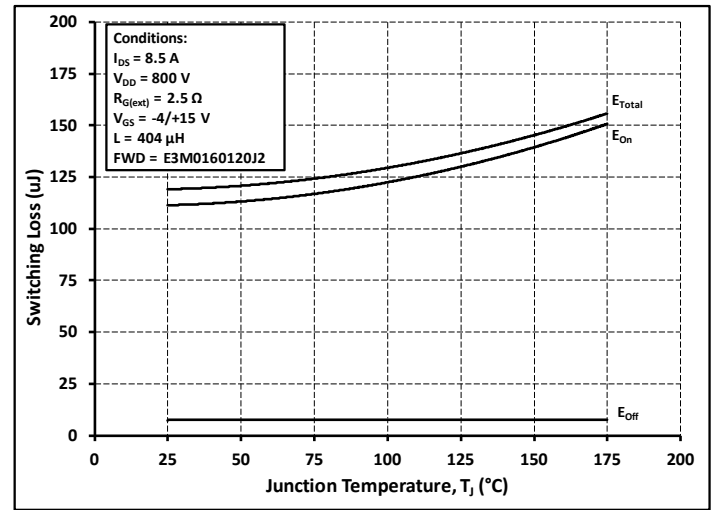
Figure 25. Clamped Inductive Switching Energy vs.  $R_{G(\text{ext})}$ 

Figure 26. Clamped Inductive Switching Energy vs. Temperature

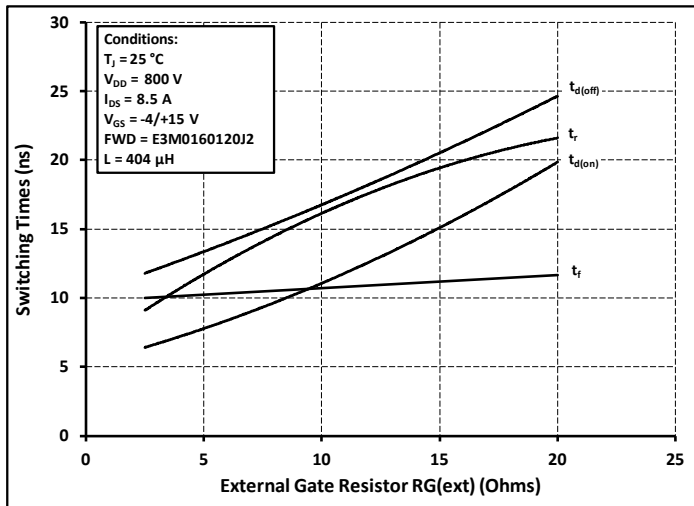
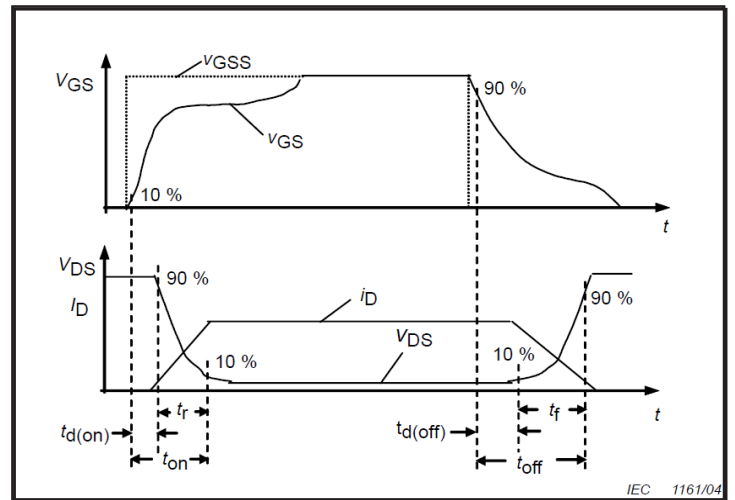
Figure 27. Switching Times vs.  $R_{G(\text{ext})}$ 

Figure 28. Switching Times Definition



## Test Circuit Schematic

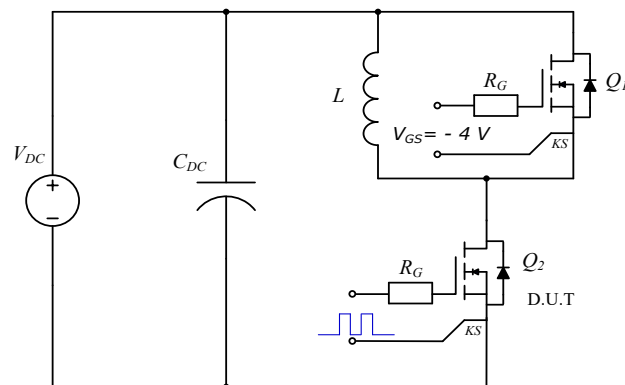
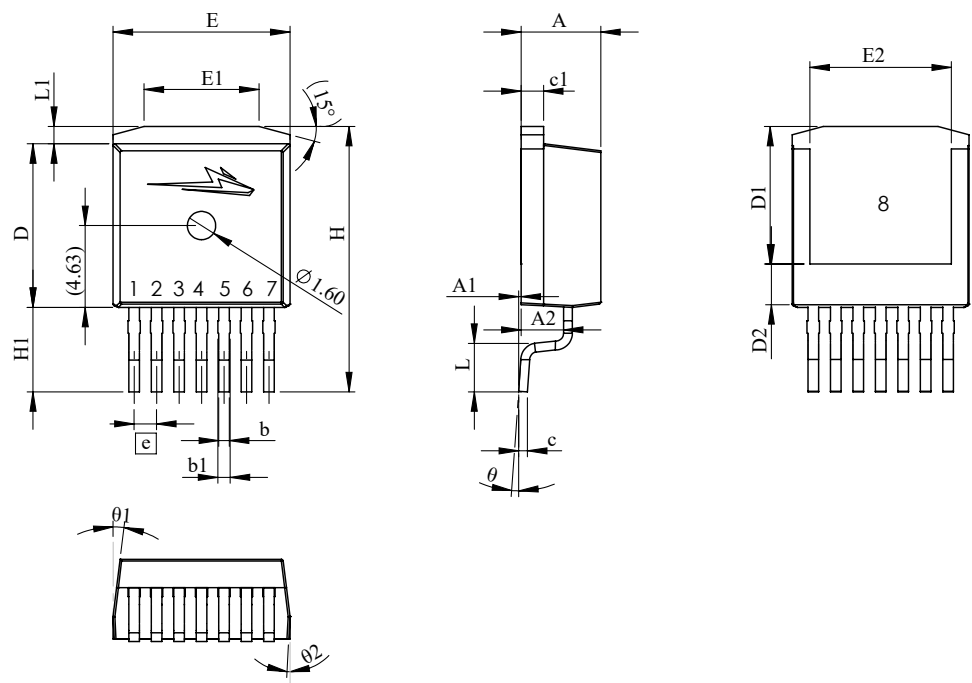


Figure 29. Clamped Inductive Switching Waveform Test Circuit



Package Dimensions



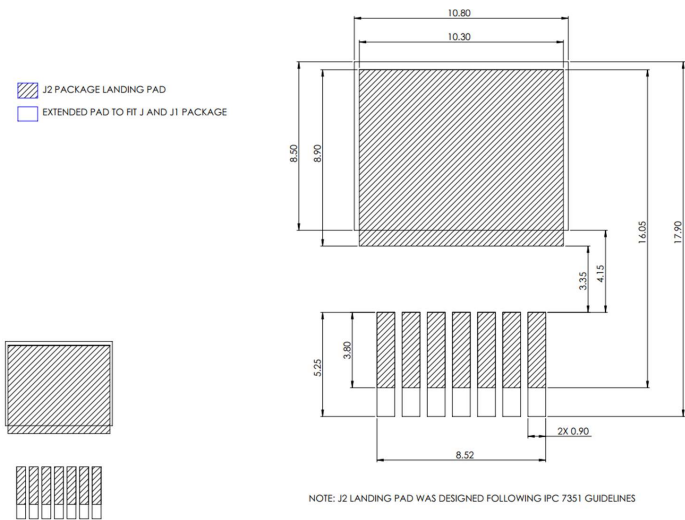
SYMBOL	MIN (mm)	MAX (mm)
A	4.30	4.70
A1	0.00	0.25
A2	2.20	2.60
b	0.52	0.72
b1	0.60	0.80
c	0.42	0.62
c1	1.07	1.47
D	9.05	9.45
D1	7.58	7.98
D2	2.05	2.45
E	9.80	10.20
E1	6.30	6.97
E2	7.80	8.20
e	1.27 BSC	
H	14.87	15.27
H1	4.55	4.95
L	2.48	2.88
L1	0.87	1.27
θ	0°	8°
θ1	4°	10°
θ2	0°	6°

1	GATE
2	KELVIN
3	SOURCE
4	
5	
6	
7	DRAIN
8	

- NOTE
- 1. ALL METAL SURFACES ARE TIN PLATED (MATTE), EXCEPT AREA OF CUT.
  - 2. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
  - 3. ALL DIMENSIONS ARE LISTED IN MILLIMETERS. ANGLES ARE IN DEGREES.
  - 4. PACKAGE BURR FLASH SIZE (0.5 mm) IS NOT INCLUDED IN THE DIMENSIONS

Recommended Solder Pad Layout

All dimensions in mm



Revision history

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Document Version	Date of release	Descriptiion of changes
1.0	December 2023	Initial release



## Notes & Disclaimer

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